

NASCO NO CLEAN FLUX

01 DEC 2010

FEATURES

VERY LOW SOLIDS
NON-CORROSIVE RESIDUES
FAST WETTING
TACK-FREE RESIDUES

BENEFITS

ELIMINATES THE NEED FOR CLEANING
HIGH SIR ASSEMBLIES
DEFECT-FREE SOLDERING
ACCURATE PIN TESTING

DESCRIPTION

NASCO NCF IS AN EFFICIENT HALIDE-FREE AND ROSIN FREE, LOW SOLIDS, NO-CLEAN FLUX. AFTER SOLDERING, A SMALL AMOUNT OF BARELY VISIBLE RESIDUE IS LEFT WHICH IS TACK-FREE AND NON-CORROSIVE.

USE

NASCO NCF IS FOR FOAM, SPRAY AND WAVE APPLICATIONS. TOPSIDE PREHEAT TEMPERATURES OF 80-105 DEGREES CELSIUS ARE RECOMMENDED.

PHYSICAL PROPETIES

APPERANCE: CLEAR, YELLOWISH-COLOURLESS LIQUID

SOLIDS CONTENT: 2.2%

SPECIFIC GRACITY @20 °C: 0.800+/- .005

ACID NUMBER (mg KOH/g): 17+/-1.0

FLASH POINT (T.C.C): 16 °C

CORROSION AND ELECTRICAL TESTING

CORROSION TESTING

Test	Requirement	Results
IPC/Bellcore Copper Mirror Test	No compleat removal of copper	Passes
Halide-silver chromate paper method	No detection of halide	Passes
IPC-SF-818-day Copper corrosion Test	No evidence of corrosion	Passes

SURFACE INSULATION RESISTANCE (VALUES IN Ohms)

Method	Conditions	Requirement	Results
IPC-SF-818	85 °C/85%RH	1.0X10 ⁸ min .	>1.0X10 ¹⁰
Class3 , Not Cleaned	7 Days		